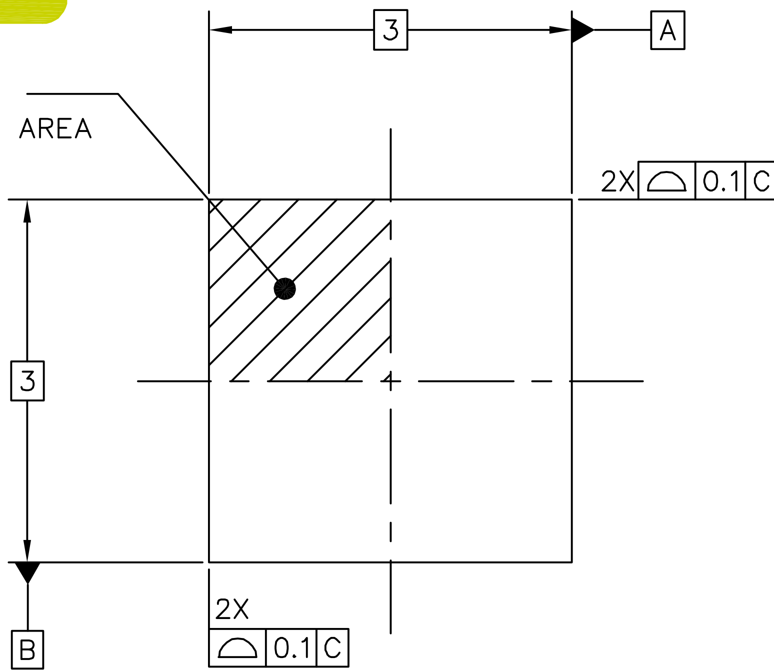

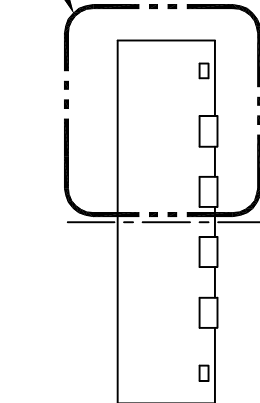

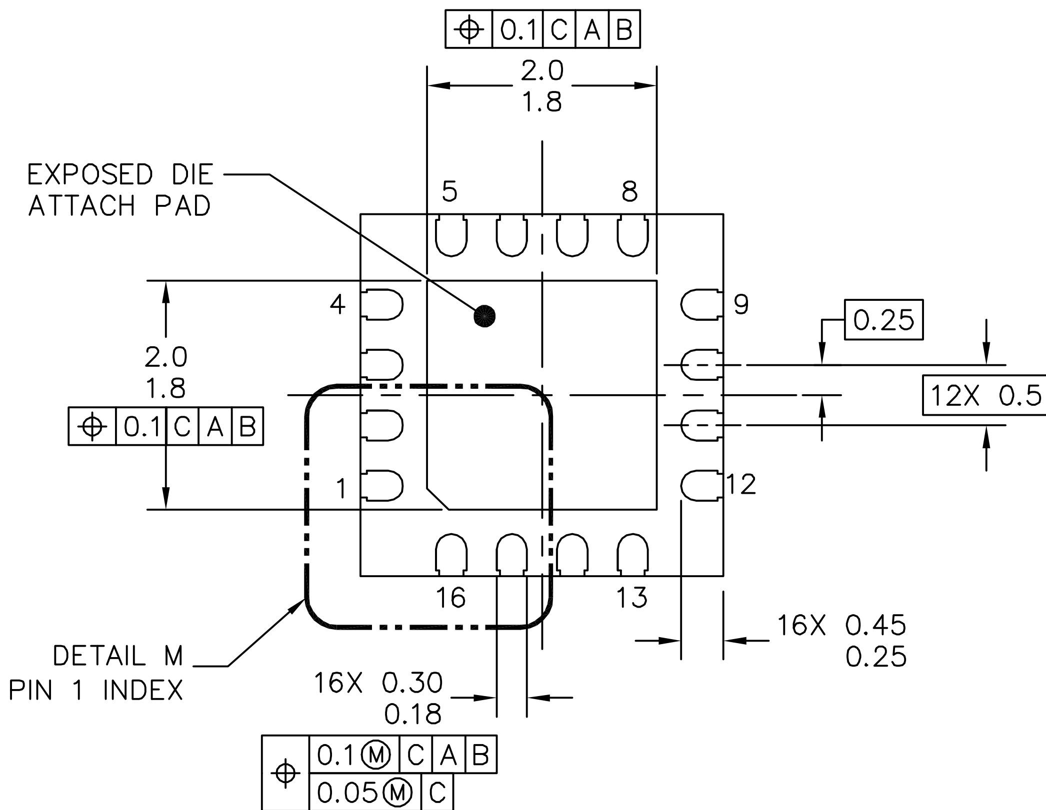

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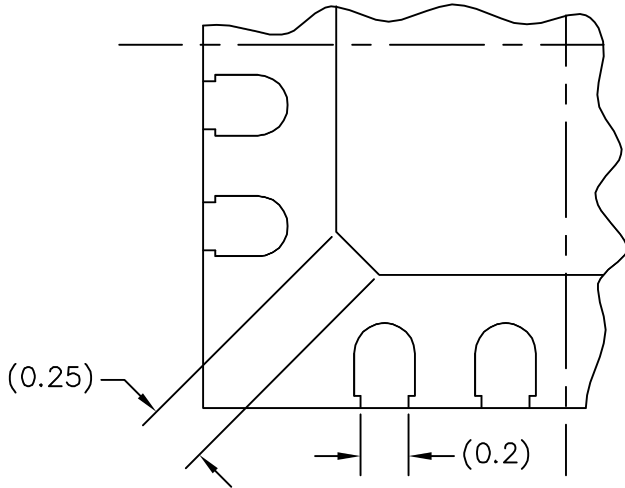
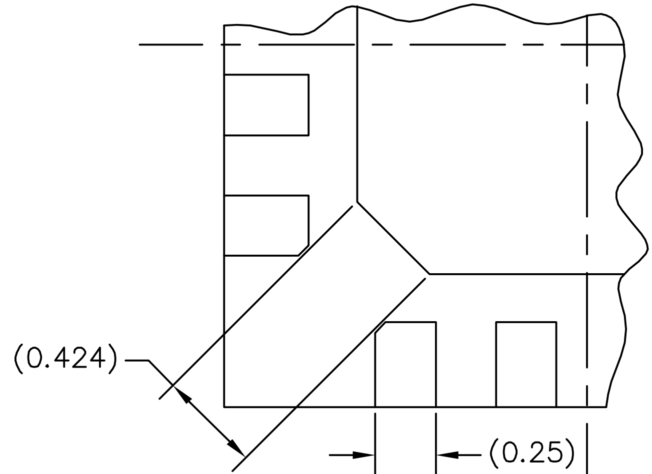
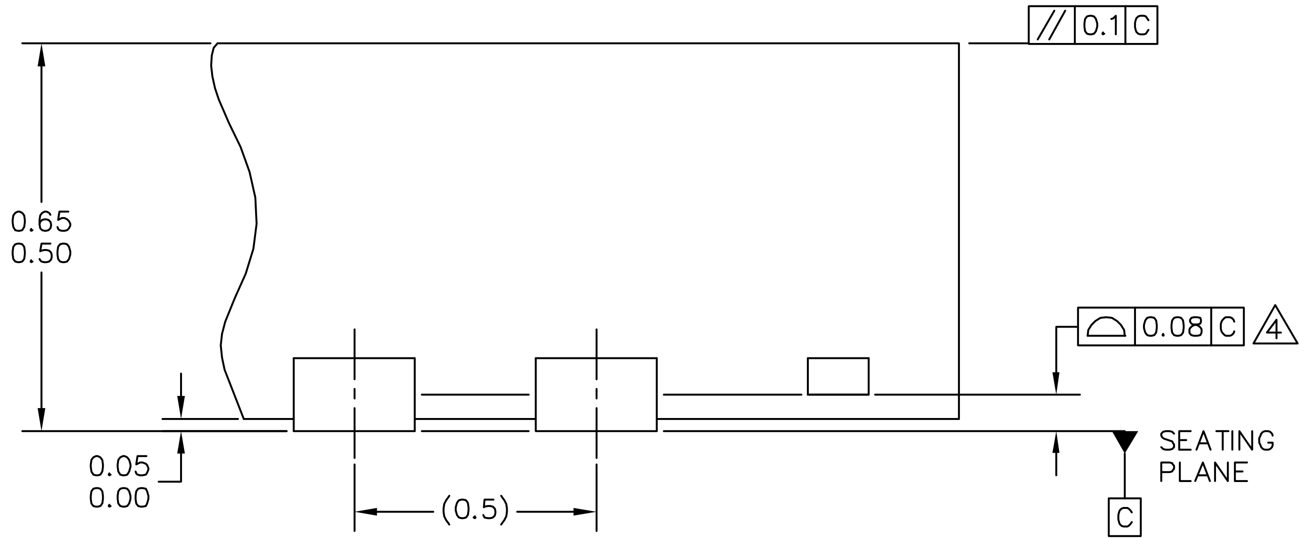
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: QFN, THERMALLY ENHANCED, 3X3X0.65 PKG, 0.5 PITCH, 16 TERMINAL, TYPE–E LEAD	DOCUMENT NO: 98ASA00525D	REV: A
	STANDARD: NON–JEDEC	
	SOT1581–2	12 JAN 2016



DETAIL M
OPTION 1
PIN 1 BACKSIDE IDENTIFIER



DETAIL M
OPTION 2
PIN 1 BACKSIDE IDENTIFIER



DETAIL G
VIEW ROTATED 90° CW

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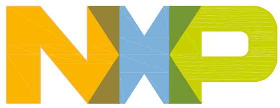

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.

3. THIS IS NON—JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

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	SOT1581—2 12 JAN 2016